



## SMB Plastic-Encapsulate Diodes

### S210B THRU S220B Schottky Rectifier Diodes

#### Features

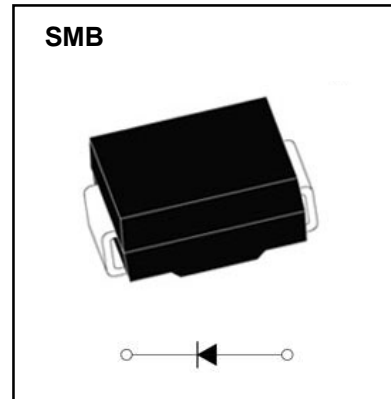
- $I_{F(AV)}$  2A
- $V_{RRM}$  100V-200V
- High surge current capability
- Polarity: Color band denotes cathode

#### Applications

- Rectifier

#### Marking

- S2XB
- X : From 10 To 20



#### Limiting Values(Absolute Maximum Rating)

| Item                                 | Symbol      | Unit             | Test Conditions  | S2         |     |
|--------------------------------------|-------------|------------------|--|------------|-----|
|                                      |             |                  |  | 10B        | 20B |
| Repetitive Peak Reverse Voltage      | $V_{RRM}$   | V                |  | 100        | 200 |
| Maximum RMS Voltage                  | $V_{RMS}$   | V                |  | 100        | 200 |
| Average Forward Current              | $I_{F(AV)}$ | A                | 60Hz Half-sine wave,<br>Resistance load, $T_a=130^\circ\text{C}$ | 2.0        |     |
| Surge(Non-repetitive)Forward Current | $I_{FSM}$   | A                | 60Hz Half-sine wave,<br>1 cycle, $T_a=25^\circ\text{C}$          | 60         |     |
| Junction Temperature                 | $T_J$       | $^\circ\text{C}$ |  | -55 ~ +175 |     |
| Storage Temperature                  | $T_{STG}$   | $^\circ\text{C}$ |  | -55 ~ +175 |     |

#### Electrical Characteristics (T =25°C Unless otherwise specified)

| Item                        | Symbol           | Unit                      | Test Condition                | S2                      |      |
|-----------------------------|------------------|---------------------------|-------------------------------|-------------------------|------|
|                             |                  |                           |                               | 10B                     | 20B  |
| Peak Forward Voltage        | $V_F$            | V                         | $I_F=2.0\text{A}$             | 0.82                    | 0.92 |
| Peak Reverse Current        | $I_{RRM1}$       | $\mu\text{A}$             | $V_{RM}=V_{RRM}$              | $T_a=25^\circ\text{C}$  |      |
|                             | $I_{RRM2}$       |                           |                               | $T_a=125^\circ\text{C}$ |      |
| Thermal Resistance(Typical) | $R_{\theta J-A}$ | $^\circ\text{C}/\text{W}$ | Between junction and ambient  | 75                      |      |
|                             | $R_{\theta J-L}$ |                           | Between junction and terminal | 25                      |      |
| Maximum Tcase               | $T_C$            | $^\circ\text{C}$          | Enclosure temperature         | 148                     |      |

#### Notes:

Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.2" x 0.2" (5.0 mm x 5.0 mm) copper pad areas

# Typical Characteristics

FIG.1: FORWARD CURRENT DERATING CURVE

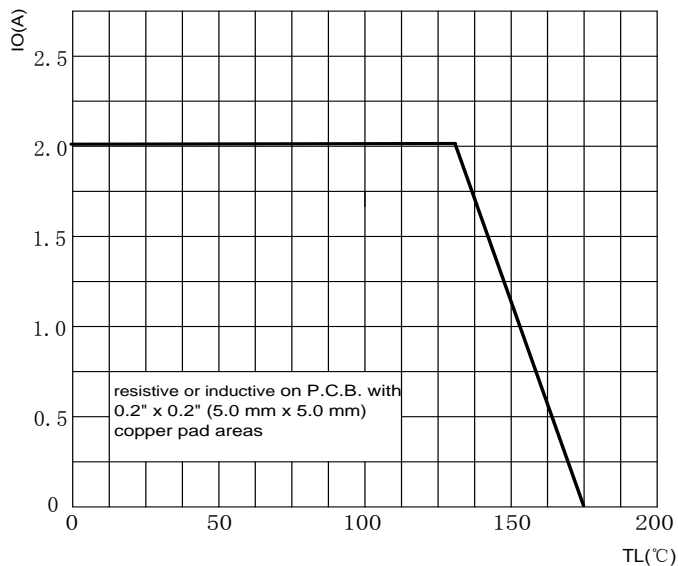


FIG.2: MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

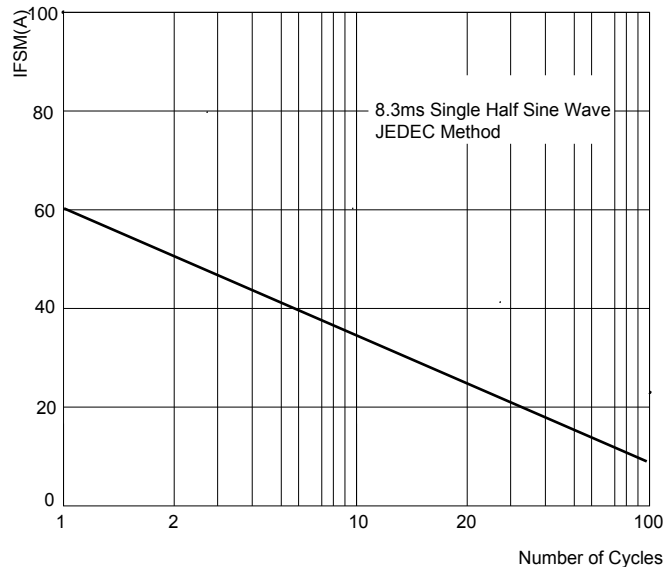


FIG.3: TYPICAL FORWARD CHARACTERISTICS

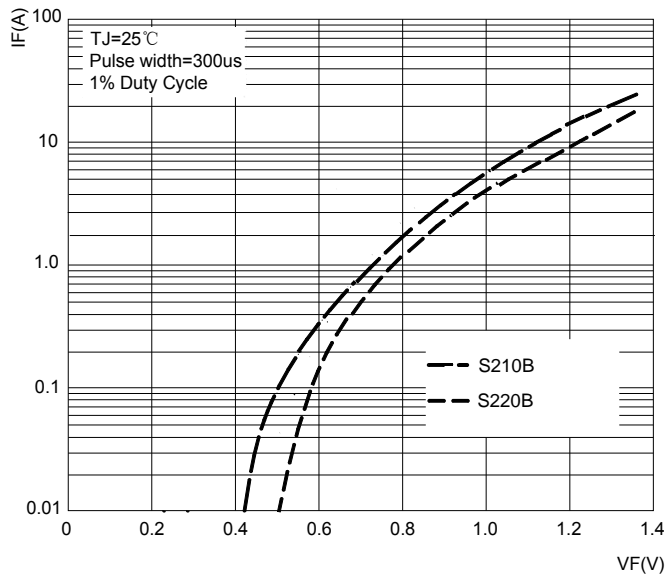
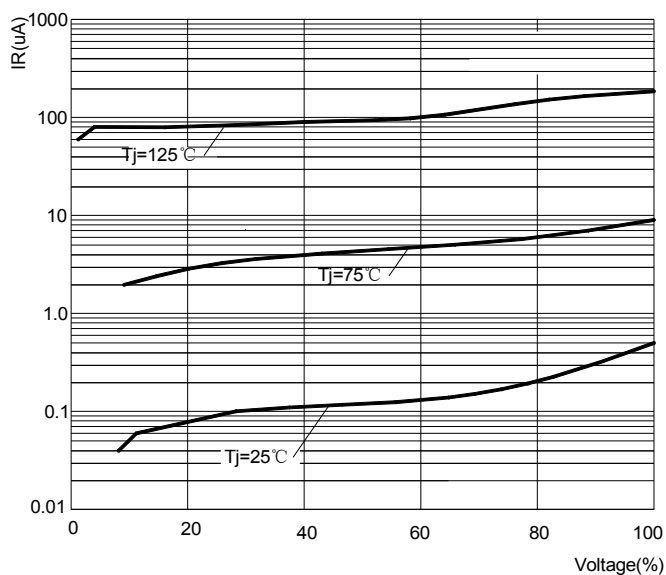
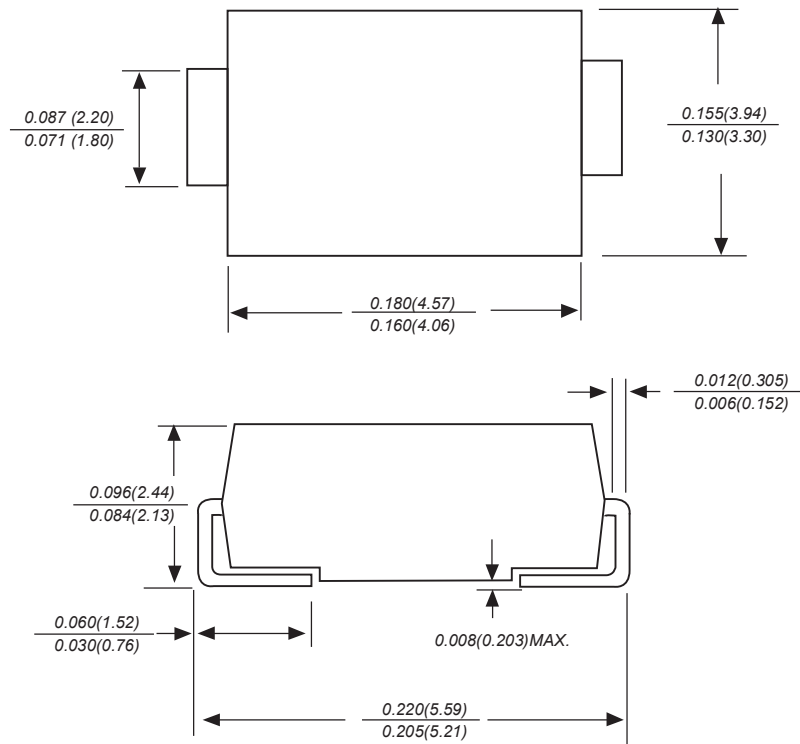


FIG.4: TYPICAL REVERSE CHARACTERISTICS

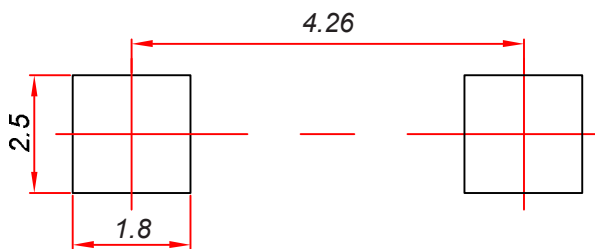


## SMB Package Outline Dimensions



Dimensions in inches and (millimeters)

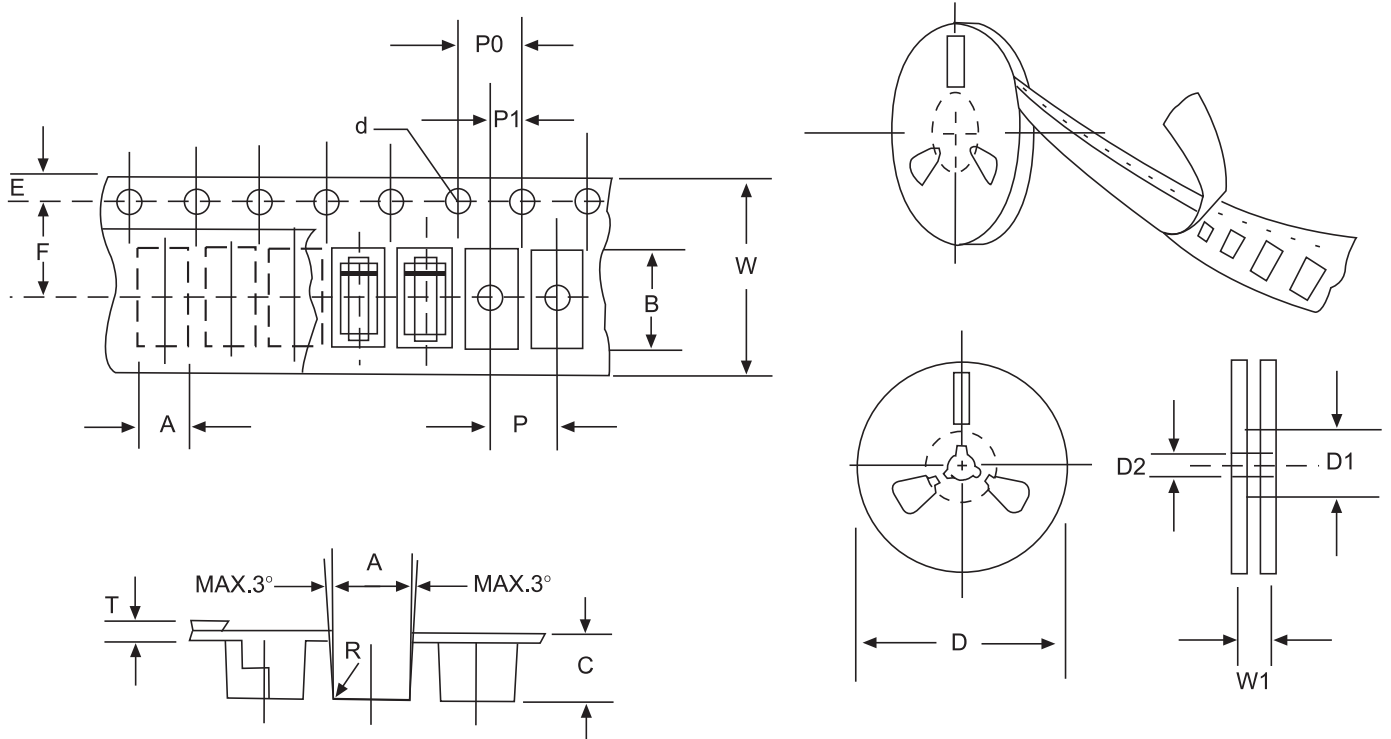
## SMB Suggested Pad Layout



### Note:

1. Controlling dimension: in millimeters.
2. General tolerance:  $\pm 0.05$ mm.
3. The pad layout is for reference purposes only.

# Reel Taping Specifications For Surface Mount Devices-SMBG



**FIG: CONFIGURATION OF SURFACE MOUNTED DEVICES TAPING**

| ITEM                  | SYMBOL | SMBG mm(inch)          |
|-----------------------|--------|------------------------|
| Carrier width         | A      | 4.09±0.1(0.161±0.004)  |
| Carrier length        | B      | 5.82±0.1(0.229±0.004)  |
| Carrier depth         | C      | 2.50±0.1(0.100±0.004)  |
| Sprocket hole         | d      | 1.55±0.05(0.061±0.002) |
| Reel outside diameter | D      | 330±2.0(13±0.079)      |
| Reel inner diameter   | D1     | 75±1.0 ( 2.95 ±0.039)  |
| Feed hole diameter    | D2     | 13±0.5(0.512±0.020)    |
| Stroket hole position | E      | 1.75±0.1(0.069±0.004)  |
| Punch hole position   | F      | 5.65±0.05(0.222±0.002) |
| Punch hole pitch      | P      | 8.0±0.1(0.315±0.004)   |
| Sprocket hole pitch   | P0     | 4.0±0.1(0.157±0.004)   |
| Embossment center     | P1     | 2.0±0.1(0.079±0.004)   |
| Total tape thickness  | T      | 0.32±0.1(0.013±0.004)  |
| Tape width            | W      | 12.0±0.2(0.472±0.008)  |
| Reel width            | W1     | 16.8±2.0(0.661±0.079)  |

NOTE: Devices are packed in accordance with EIA standard RS-481-A and specification given above.